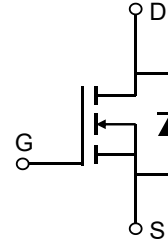


Description

Features

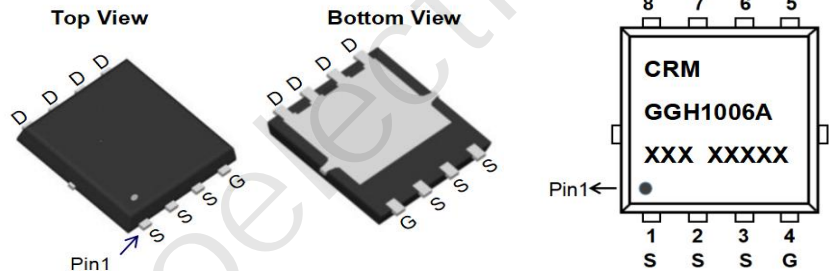
- 100V, 102A
 $R_{DS(ON)}$ Typ = 5.8mΩ @ $V_{GS} = 10V$
 Advanced Split Gate Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔV_{ds} TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMGGH1006A	CRMGGH1006A	PDFN5x6-8L	TAPING	13"	5000	50000

Absolute Maximum Ratings (@ $T_J = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Value	Units	
V _{DS}	Drain-to-Source Voltage	100	V	
V _{GS}	Gate-to-Source Voltage	±20	V	
I _D	Continuous Drain Current	T _C = 25°C	102	A
		T _C = 100°C	61.2	A
I _{DM}	Pulsed Drain Current ⁽¹⁾	408	A	
E _{AS}	Single Pulsed Avalanche Energy ⁽²⁾	150	mJ	
P _D	Power Dissipation	T _C = 25°C	132	W
R _{θJC}	Thermal Resistance, Junction to Case	0.95	°C/W	
T _J , T _{STG}	Junction & Storage Temperature Range	-55 to 150	°C	

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
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Off Characteristics

$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	100	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 100\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	± 100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.4	3	3.6	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 10\text{V}, I_D = 30\text{A}$	-	5.8	7.5	mΩ

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 50\text{V},$ $f = 1\text{MHz}$	-	1603	-	pF
C_{oss}	Output Capacitance		-	606	-	pF
C_{rss}	Reverse Transfer Capacitance		-	13	-	pF
Q_g	Total Gate Charge	$V_{GS} = 0 \text{ to } 10\text{V}$ $V_{DS} = 50\text{V}, I_D = 25\text{A}$	-	25	-	nC
Q_{gs}	Gate Source Charge		-	12	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	5	-	nC

Switching Characteristics

$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = 10\text{V}, V_{DD} = 50\text{V}$ $I_D = 25\text{A}, R_{GEN} = 3\Omega$	-	12	-	ns
t_r	Turn-On Rise Time		-	70	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	35	-	ns
t_f	Turn-Off Fall Time		-	15	-	ns

Drain-Source Diode Characteristics and Max Ratings

I_S	Maximum Continuous Drain to Source Diode Forward Current	$V_{GS} = 0\text{V}, I_S = 30\text{A}$	-	-	102	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	408	A
V_{SD}	Drain to Source Diode Forward Voltage		-	-	1.2	V
t_{rr}	Body Diode Reverse Recovery Time		-	65	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	90	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = 50\text{V}$, $V_G = 10\text{V}$, $R_G = 25\text{ohm}$, $L = 0.5\text{mH}$, $I_{AS} = 24.5\text{A}$
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Test Circuit

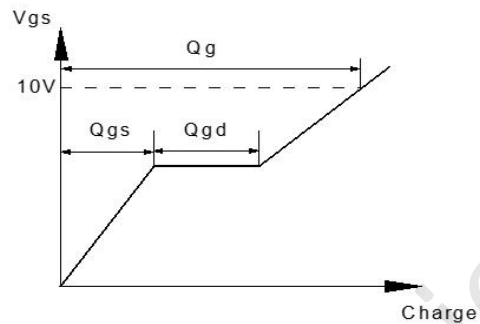
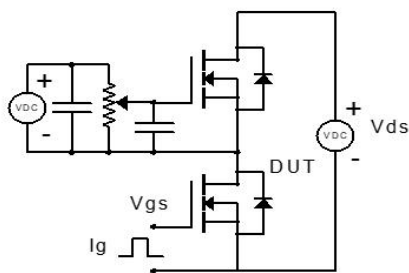


Figure 1: Gate Charge Test Circuit & Waveform



Figure 2: Resistive Switching Test Circuit & Waveform

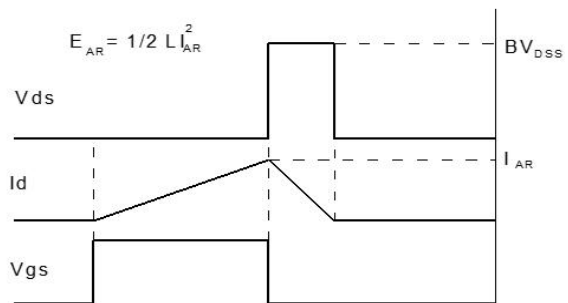
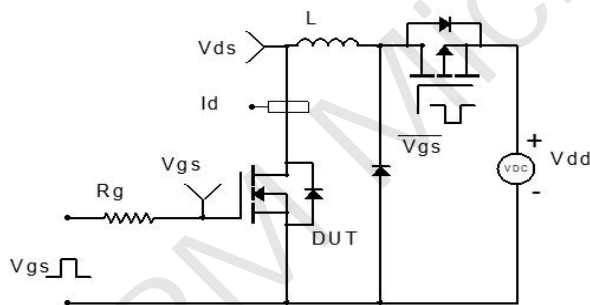


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

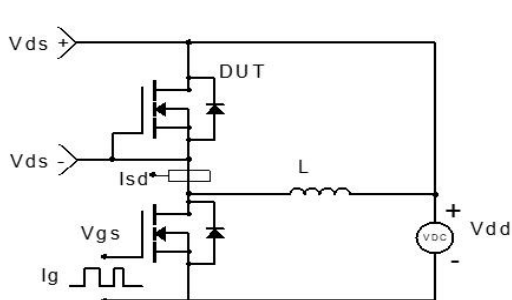
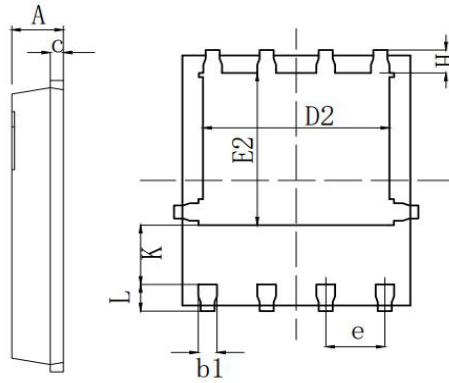
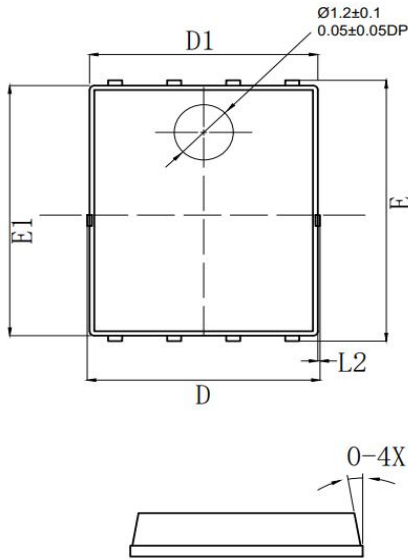


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(PDFN5x6-8L)



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.90	1.00	1.10
b	0.25	0.30	0.35
b1	0.30	0.40	0.45
c	0.22	0.25	0.28
D	—	—	5.30
D1	4.90	5.05	5.20
D2	3.90REF		
E	6.00	6.15	6.30
E1	5.70	5.85	6.00
E2	3.50REF		
e	1.10	1.27	1.40
H	0.51	0.61	0.71
K	1.10	—	—
L	0.51	0.61	0.71
L2	—	—	0.10
Φ	8°	—	12°

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